Module specifications are nominal values based on the hot-side temperature indicated. Thermoelectric material parameter tolerance is +/-10%.

In no case should the module temperature be allowed to exceed its maximum operation/storage temperature.

Please review all product and technical information, Thermoelectric Module Mounting Procedure, parameter definitions, FAQ's, and ordering information posted on our website before purchasing or using this product.

Optional Features and Notes:
- Add "P" to part number for sealing module with epoxy potting.
- Module includes 30 μm nickel metallization on hot and cold sides.
- The metallization does not include pre-tinning.
- Performance graphs include thermal resistance of substrates.
Unpotted TE-11-0.6-1.5 at a hot-side temperature of 30 °C
Potted TE-11-0.6-1.5 at a hot-side temperature of 30 °C
Unpotted TE-11-0.6-1.5 at a hot-side temperature of 50 °C
Potted TE-11-0.6-1.5 at a hot-side temperature of 50 °C
Unpotted TE-11-0.6-1.5 at a hot-side temperature of 70 °C
Potted TE-11-0.6-1.5 at a hot-side temperature of 70 °C